#### PIN diodes

# MA2JP02

### Silicon epitaxial planar type

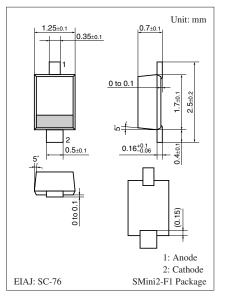
For high frequency switch

#### Features

- Small terminal capacitance C<sub>t</sub>
- $\bullet$  Small forward dynamic resistance  $r_{\rm f}$
- Miniature package and surface mounting type

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit		
Reverse voltage	V <sub>R</sub>	60	V		
Forward current	$I_{\rm F}$	100	mA		
Power dissipation	PD	150	mW		
Junction temperature	Tj	150	°C		
Storage temperature	T <sub>stg</sub>	-55 to +150	°C		



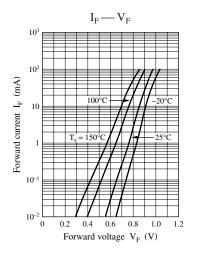
#### Marking Symbol: 3F

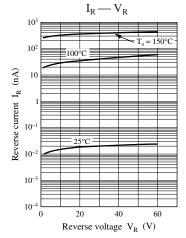
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	$I_F = 10 \text{ mA}$			1.0	V
Reverse current	I <sub>R</sub>	$V_R = 60 V$			100	nA
Terminal capacitance	Ct	$V_R = 1 V, f = 1 MHz$			0.5	pF
Forward dynamic resistance	r <sub>f</sub>	$I_F = 10 \text{ mA}, \text{ f} = 100 \text{ MHz}$			2.0	Ω

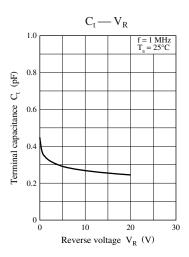
#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

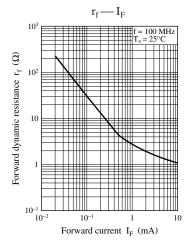
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

## Panasonic









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